1 Package summary

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<td>actual quantity of termination</td>
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2 Package outline

Figure 1. Package outline WLCSP56 (SOT1890-3)
3 Soldering

Figure 2. Reflow soldering footprint part1 for WLCSP56 (SOT1890-3)
PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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Figure 4. Reflow soldering footprint part3 for WLCSP56 (SOT1890-3)
NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.


3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.

4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.

5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

6. THIS PACKAGE HAS A BACK SIDE COATING THICKNESS OF 0.025.

Figure 5. Package outline note WLCSP56 (SOT1890-3)
4 Legal information

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